

IMPACT

TE Internal #: 8-2149979-3 High Speed Backplane Connectors, 72 Position, Mating Alignment, Keyed Mating Alignment Type, 12 Row, 6 Column, PCB Mount Header, Vertical, IMPACT

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors



Number of Positions: 72 Row-to-Row Spacing: 1.35 mm [.053 in] Mating Alignment: With

Mating Alignment Type: Keyed

Number of Rows: 12

Features

Product Type Features

Signal ArrangementDifferentialConnector SystemBoard-to-BoardConnector & Contact Terminates ToPrinted Circuit Board

PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Fully Shrouded
Configuration Features	
Number of Ground Positions	24
Number of Pairs	24
Stackable	No
Number of Signal Positions	48
Number of Positions	72
Number of Rows	12
Number of Columns	6
PCB Mount Orientation	Vertical
Guide Location	Right
Electrical Characteristics	
Impedance	100 Ω
Operating Voltage	30 VAC

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Signal Characteristics

Number of Differential Pairs per Column 4 Data Rate 20–25 Gb/s Sody Features Black Primary Product Color Black contact Mating Area Length 5.5 mm[.217 in PCB Contact Termination Area Plating Material Thickness .76 – 1.52 µm[.2 Contact Layout Inline Contact Mating Area Plating Material Thickness .76 µm[.2 Contact Termination Area Plating Material Finish Matte Contact Shape & Form Dual Beam Contact Underplating Material	
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Mating Alignment Type Keyed	
Connector Mounting Type Board Mount	

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Number of Shrouded Sides	3
End Wall Location	Right
Housing Material	LCP (Liquid Crystal Polymer)
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	19.3 mm[.76 in]
Connector Height	11.95 mm[.47 in]
Connector Width	20.8 mm[.819 in]
PCB Thickness (Recommended)	1 mm[.039 in]
PCB Hole Diameter	.39 mm[.015 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Compatible With Approved Standards Products	CSA Certified, UL E28476

UL Flammability Rating

UL 94V-0

Packaging Features

Packaging Method

Box & Tube, Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

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Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

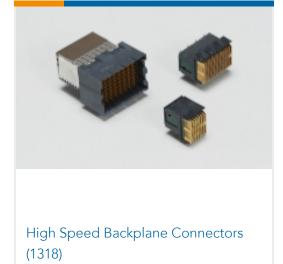
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



TE Part # 2132739-1 IMP100S,R,RA4P6C,UG,39

Also in the Series IMPACT



Customers Also Bought



High Speed Backplane Connectors, 72 Position, Mating Alignment, Keyed Mating Alignment Type, 12 Row, 6 Column, PCB Mount Header, Vertical, IMPACT





Documents

Product Drawings IMP100,S,H,V4P6C,LG,REW39

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_8-2149979-3_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_8-2149979-3_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_8-2149979-3_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English

Agency Approvals Agency Approval Document

English